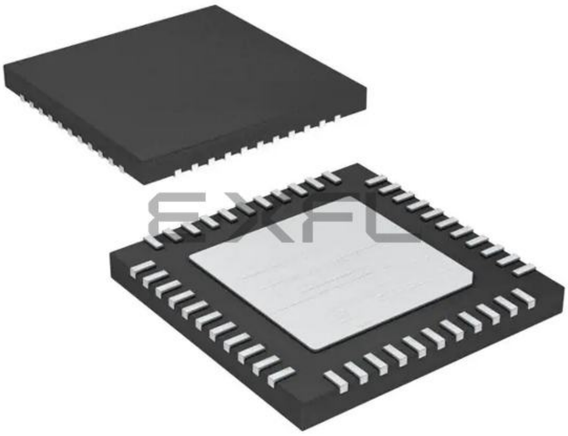


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx110f016d-v-ml

TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at **docerrors@microchip.com**. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

http://www.microchip.com

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000000A is version A of document DS30000000).

Errata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

- Microchip's Worldwide Web site; **http://www.microchip.com**
- Your local Microchip sales office (see last page)

When contacting a sales office, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at **www.microchip.com** to receive the most current information on all of our products.

REGISTER 4-1: BMXCON: BUS MATRIX CONFIGURATION REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	—	—	—	BMX ERRIXI	BMX ERRICD	BMX ERRDMA	BMX ERRDS	BMX ERRIS
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	R/W-1	U-0	U-0	U-0	R/W-0	R/W-0	R/W-1
	—	BMX WSDRM	—	—	—	BMXARB<2:0>		

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared

bit 31-21 **Unimplemented:** Read as ‘0’

bit 20 **BMXERRIXI:** Enable Bus Error from IXI bit

1 = Enable bus error exceptions for unmapped address accesses initiated from IXI shared bus
0 = Disable bus error exceptions for unmapped address accesses initiated from IXI shared bus

bit 19 **BMXERRICD:** Enable Bus Error from ICD Debug Unit bit

1 = Enable bus error exceptions for unmapped address accesses initiated from ICD
0 = Disable bus error exceptions for unmapped address accesses initiated from ICD

bit 18 **BMXERRDMA:** Bus Error from DMA bit

1 = Enable bus error exceptions for unmapped address accesses initiated from DMA
0 = Disable bus error exceptions for unmapped address accesses initiated from DMA

bit 17 **BMXERRDS:** Bus Error from CPU Data Access bit (disabled in Debug mode)

1 = Enable bus error exceptions for unmapped address accesses initiated from CPU data access
0 = Disable bus error exceptions for unmapped address accesses initiated from CPU data access

bit 16 **BMXERRIS:** Bus Error from CPU Instruction Access bit (disabled in Debug mode)

1 = Enable bus error exceptions for unmapped address accesses initiated from CPU instruction access
0 = Disable bus error exceptions for unmapped address accesses initiated from CPU instruction access

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6 **BMXWSDRM:** CPU Instruction or Data Access from Data RAM Wait State bit

1 = Data RAM accesses from CPU have one wait state for address setup
0 = Data RAM accesses from CPU have zero wait states for address setup

bit 5-3 **Unimplemented:** Read as ‘0’

bit 2-0 **BMXARB<2:0>:** Bus Matrix Arbitration Mode bits

111 = Reserved (using these Configuration modes will produce undefined behavior)
•
•
•
011 = Reserved (using these Configuration modes will produce undefined behavior)
010 = Arbitration Mode 2
001 = Arbitration Mode 1 (default)
000 = Arbitration Mode 0

REGISTER 6-2: RSWRST: SOFTWARE RESET REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	W-0, HC
	—	—	—	—	—	—	—	SWRST[(1)]

Legend: HC = Cleared by hardware
R = Readable bit W = Writable bit U = Unimplemented bit, read as ‘0’
-n = Value at POR ‘1’ = Bit is set ‘0’ = Bit is cleared x = Bit is unknown

bit 31-1 **Unimplemented:** Read as ‘`0`’

bit 0 **SWRST:** Software Reset Trigger bit[(1)]
`1` = Enable Software Reset event
`0` = No effect

Note 1: The system unlock sequence must be performed before the SWRST bit is written. Refer to **Section 6. “Oscillator”** (DS60001112) in the *“PIC32 Family Reference Manual”* for details.

11.0 I/O PORTS

> **Note:** This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 12. "I/O Ports"** (DS60001120), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

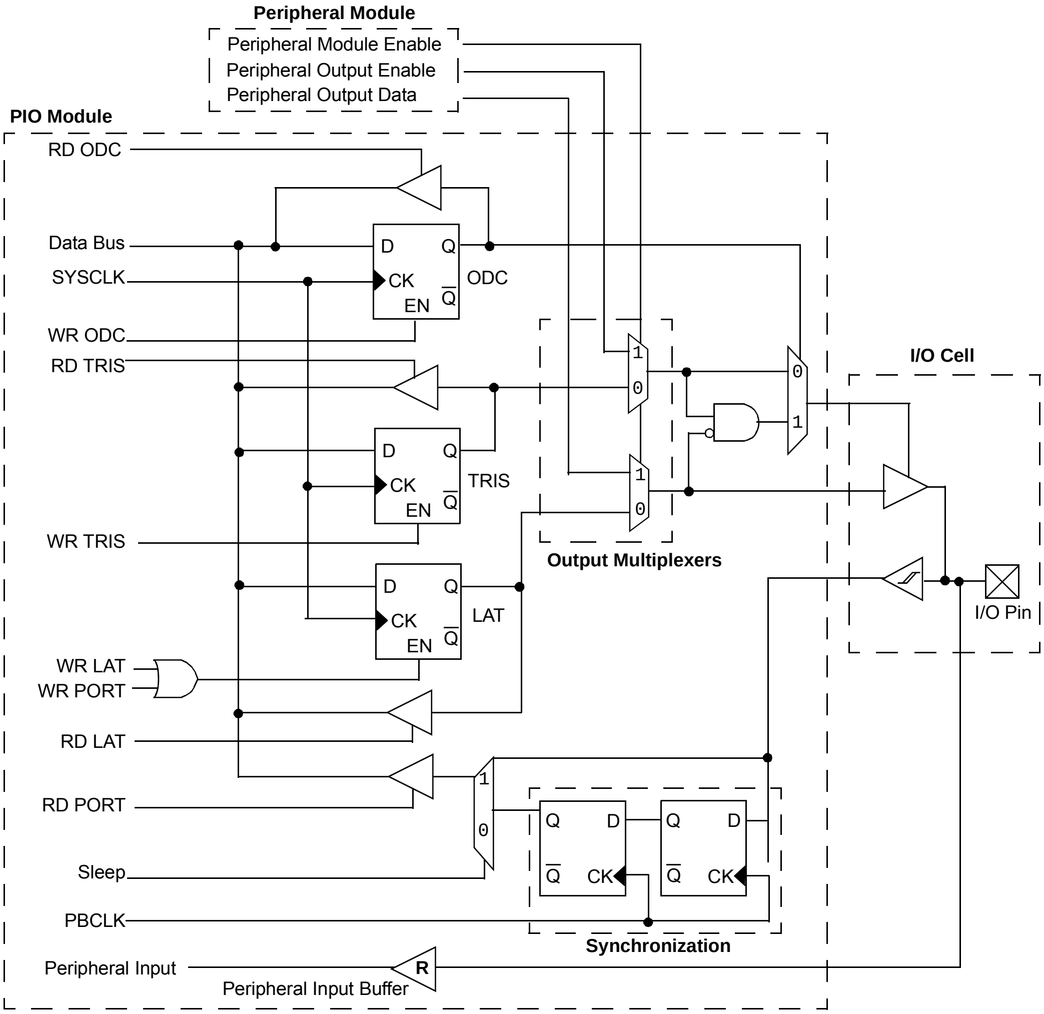
General purpose I/O pins are the simplest of peripherals. They allow the PIC® MCU to monitor and control other devices. To add flexibility and functionality, some pins are multiplexed with alternate functions. These functions depend on which peripheral features are on the device. In general, when a peripheral is functioning, that pin may not be used as a general purpose I/O pin.

Key features of this module include:

- Individual output pin open-drain enable/disable
- Individual input pin weak pull-up and pull-down
- Monitor selective inputs and generate interrupt when change in pin state is detected
- Operation during Sleep and Idle modes
- Fast bit manipulation using CLR, SET, and INV registers

Figure 11-1 illustrates a block diagram of a typical multiplexed I/O port.

FIGURE 11-1: BLOCK DIAGRAM OF A TYPICAL MULTIPLEXED PORT STRUCTURE



Legend: R = Peripheral input buffer types may vary. Refer to Table 1-1 for peripheral details.

Note: This block diagram is a general representation of a shared port/peripheral structure and is only provided for illustration purposes. The actual structure for any specific port/peripheral combination may be different than it is shown here.

NOTES:

REGISTER 16-1: OCxCON: OUTPUT COMPARE ‘x’ CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON[1]	—	SIDL	—	—	—	—	—
7:0	U-0	U-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	OC32	OCFLT[2]	OCTSEL	OCM<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as ‘0’

bit 15 **ON:** Output Compare Peripheral On bit[1]
1 = Output Compare peripheral is enabled
0 = Output Compare peripheral is disabled

bit 14 **Unimplemented:** Read as ‘0’

bit 13 **SIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12-6 **Unimplemented:** Read as ‘0’

bit 5 **OC32:** 32-bit Compare Mode bit
1 = OCxR<31:0> and/or OCxRS<31:0> are used for comparisons to the 32-bit timer source
0 = OCxR<15:0> and OCxRS<15:0> are used for comparisons to the 16-bit timer source

bit 4 **OCFLT:** PWM Fault Condition Status bit[2]
1 = PWM Fault condition has occurred (cleared in hardware only)
0 = No PWM Fault condition has occurred

bit 3 **OCTSEL:** Output Compare Timer Select bit
1 = Timer3 is the clock source for this Output Compare module
0 = Timer2 is the clock source for this Output Compare module

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits
111 = PWM mode on OCx; Fault pin enabled
110 = PWM mode on OCx; Fault pin disabled
101 = Initialize OCx pin low; generate continuous output pulses on OCx pin
100 = Initialize OCx pin low; generate single output pulse on OCx pin
011 = Compare event toggles OCx pin
010 = Initialize OCx pin high; compare event forces OCx pin low
001 = Initialize OCx pin low; compare event forces OCx pin high
000 = Output compare peripheral is disabled but continues to draw current

Note 1: When using 1:1 PBCLK divisor, the user’s software should not read/write the peripheral’s SFRs in the SYSCLK cycle immediately following the instruction that clears the module’s ON bit.

2: This bit is only used when OCM<2:0> = ‘111’. It is read as ‘0’ in all other modes.

17.1 SPI Control Registers

TABLE 17-1: SPI1 AND SPI2 REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5800	SPI1CON	31:16	FRMEN	FRMSYNC	FRMPOL	MSSEN	FRMSYPW	FRMCNT<2:0>			MCLKSEL	—	—	—	—	—	SPIFE	ENHBUF	0000
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	DISSDI	STXISEL<1:0>		SRXISEL<1:0>		0000
5810	SPI1STAT	31:16	—	—	—	RXBUFELM<4:0>					—	—	—	TXBUFELM<4:0>					0000
		15:0	—	—	—	FRMERR	SPIBUSY	—	—	SPITUR	SRMT	SPIROV	SPIRBE	—	SPITBE	—	SPITBF	SPIRBF	0008
5820	SPI1BUF	31:16	DATA<31:0>																0000
		15:0																	0000
5830	SPI1BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	BRG<12:0>													0000
5840	SPI1CON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	SPI SGNEXT	—	—	FRM ERREN	SPI ROVEN	SPI TUREN	IGNROV	IGNTUR	AUDEN	—	—	—	AUD MONO	—	AUDMOD<1:0>		0000
5A00	SPI2CON	31:16	FRMEN	FRMSYNC	FRMPOL	MSSEN	FRMSYPW	FRMCNT<2:0>			MCLKSEL	—	—	—	—	—	SPIFE	ENHBUF	0000
		15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	DISSDI	STXISEL<1:0>		SRXISEL<1:0>		0000
5A10	SPI2STAT	31:16	—	—	—	RXBUFELM<4:0>					—	—	—	TXBUFELM<4:0>					0000
		15:0	—	—	—	FRMERR	SPIBUSY	—	—	SPITUR	SRMT	SPIROV	SPIRBE	—	SPITBE	—	SPITBF	SPIRBF	0008
5A20	SPI2BUF	31:16	DATA<31:0>																0000
		15:0																	0000
5A30	SPI2BRG	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	BRG<12:0>													0000
5A40	SPI2CON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	SPI SGNEXT	—	—	FRM ERREN	SPI ROVEN	SPI TUREN	IGNROV	IGNTUR	AUDEN	—	—	—	AUD MONO	—	AUDMOD<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table except SPIxBUF have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 “CLR, SET and INV Registers”** for more information.

REGISTER 17-3: SPIxSTAT: SPI STATUS REGISTER

bit 3	**SPITBE:** SPI Transmit Buffer Empty Status bit `1` = Transmit buffer, SPIxTXB is empty `0` = Transmit buffer, SPIxTXB is not empty Automatically set in hardware when SPI transfers data from SPIxTXB to SPIxSR. Automatically cleared in hardware when SPIxBUF is written to, loading SPIxTXB.
bit 2	**Unimplemented:** Read as ‘`0`’
bit 1	**SPITBF:** SPI Transmit Buffer Full Status bit `1` = Transmit not yet started, SPITXB is full `0` = Transmit buffer is not full Standard Buffer Mode: Automatically set in hardware when the core writes to the SPIBUF location, loading SPITXB. Automatically cleared in hardware when the SPI module transfers data from SPITXB to SPISR. Enhanced Buffer Mode: Set when CWPTR + 1 = SRPTR; cleared otherwise
bit 0	**SPIRBF:** SPI Receive Buffer Full Status bit `1` = Receive buffer, SPIxRXB is full `0` = Receive buffer, SPIxRXB is not full Standard Buffer Mode: Automatically set in hardware when the SPI module transfers data from SPIxSR to SPIxRXB. Automatically cleared in hardware when SPIxBUF is read from, reading SPIxRXB. Enhanced Buffer Mode: Set when SWPTR + 1 = CRPTR; cleared otherwise

REGISTER 23-2: CMSTAT: COMPARATOR STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	—	—	SIDL	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	R-0	R-0	R-0
	—	—	—	—	—	C3OUT	C2OUT	C1OUT

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-14 **Unimplemented:** Read as ‘`0`’

bit 13 **SIDL:** Stop in Idle Control bit

`1` = All Comparator modules are disabled when the device enters Idle mode
`0` = All Comparator modules continue to operate when the device enters Idle mode

bit 12-3 **Unimplemented:** Read as ‘`0`’

bit 2 **C3OUT:** Comparator Output bit

`1` = Output of Comparator 3 is a ‘`1`’
`0` = Output of Comparator 3 is a ‘`0`’

bit 1 **C2OUT:** Comparator Output bit

`1` = Output of Comparator 2 is a ‘`1`’
`0` = Output of Comparator 2 is a ‘`0`’

bit 0 **C1OUT:** Comparator Output bit

`1` = Output of Comparator 1 is a ‘`1`’
`0` = Output of Comparator 1 is a ‘`0`’

24.1 Comparator Voltage Reference Control Register

TABLE 24-1: COMPARATOR VOLTAGE REFERENCE REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9800	CVRCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	—	—	—	—	—	—	CVROE	CVRR	CVRSS	CVR<3:0>				0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 “CLR, SET and INV Registers”** for more information.

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

bit 24 **EDG1STAT:** Edge1 Status bit

Indicates the status of Edge1 and can be written to control edge source

`1` = Edge1 has occurred
`0` = Edge1 has not occurred

bit 23 **EDG2MOD:** Edge2 Edge Sampling Select bit

`1` = Input is edge-sensitive
`0` = Input is level-sensitive

bit 22 **EDG2POL:** Edge 2 Polarity Select bit

`1` = Edge2 programmed for a positive edge response
`0` = Edge2 programmed for a negative edge response

bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits

`1111` = C3OUT pin is selected
`1110` = C2OUT pin is selected
`1101` = C1OUT pin is selected
`1100` = PBCLK clock is selected
`1011` = IC3 Capture Event is selected
`1010` = IC2 Capture Event is selected
`1001` = IC1 Capture Event is selected
`1000` = CTED13 pin is selected
`0111` = CTED12 pin is selected
`0110` = CTED11 pin is selected
`0101` = CTED10 pin is selected
`0100` = CTED9 pin is selected
`0011` = CTED1 pin is selected
`0010` = CTED2 pin is selected
`0001` = OC1 Compare Event is selected
`0000` = Timer1 Event is selected

bit 17-16 **Unimplemented:** Read as ‘`0`’

bit 15 **ON:** ON Enable bit

`1` = Module is enabled
`0` = Module is disabled

bit 14 **Unimplemented:** Read as ‘`0`’

bit 13 **CTMUSIDL:** Stop in Idle Mode bit

`1` = Discontinue module operation when the device enters Idle mode
`0` = Continue module operation when the device enters Idle mode

bit 12 **TGEN:** Time Generation Enable bit**(1)**

`1` = Enables edge delay generation
`0` = Disables edge delay generation

bit 11 **EDGEN:** Edge Enable bit

`1` = Edges are not blocked
`0` = Edges are blocked

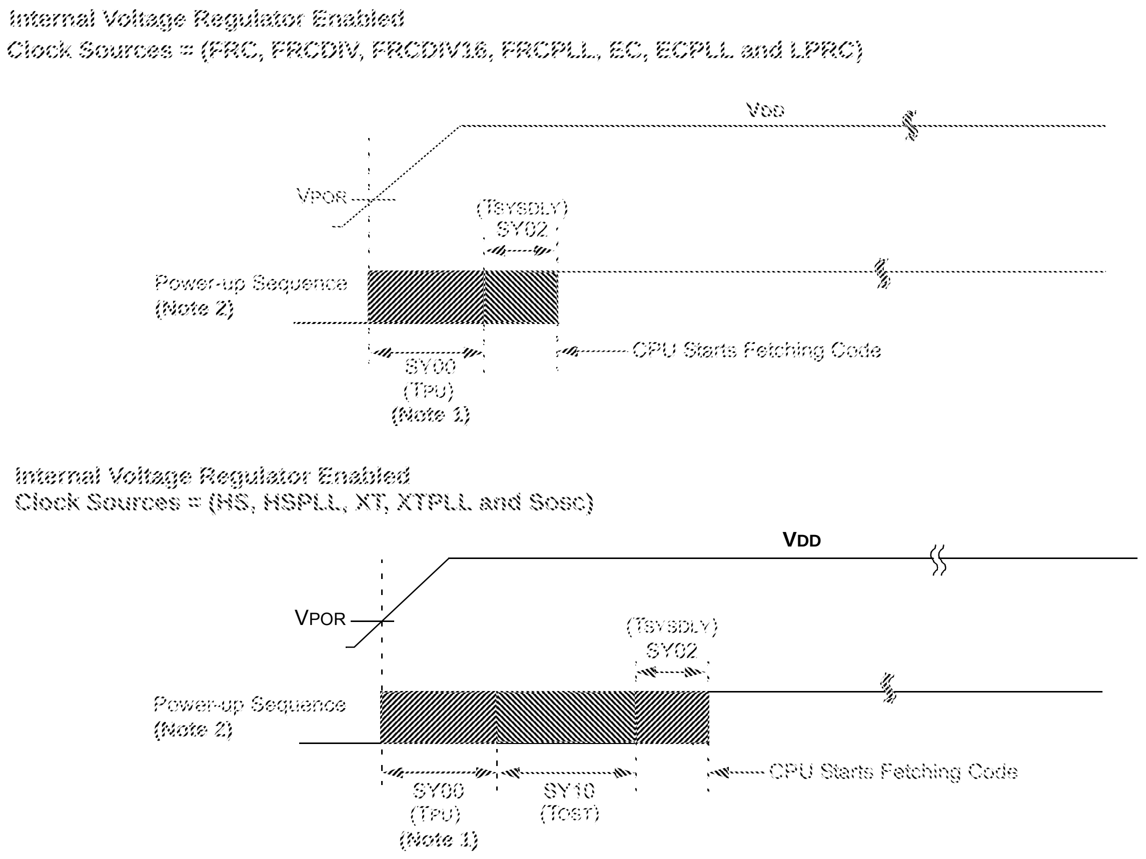
Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to ‘`1110`’ to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to ‘`1`’, performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in **Section 30.0 “Electrical Characteristics”** for current values.

4: This bit setting is not available for the CTMU temperature diode.

FIGURE 30-4: POWER-ON RESET TIMING CHARACTERISTICS



Note 1: The power-up period will be extended if the power-up sequence completes before the device exits from BOR (VDD < VDDMIN).

2: Includes interval voltage regulator stabilization delay.

FIGURE 30-5: EXTERNAL RESET TIMING CHARACTERISTICS

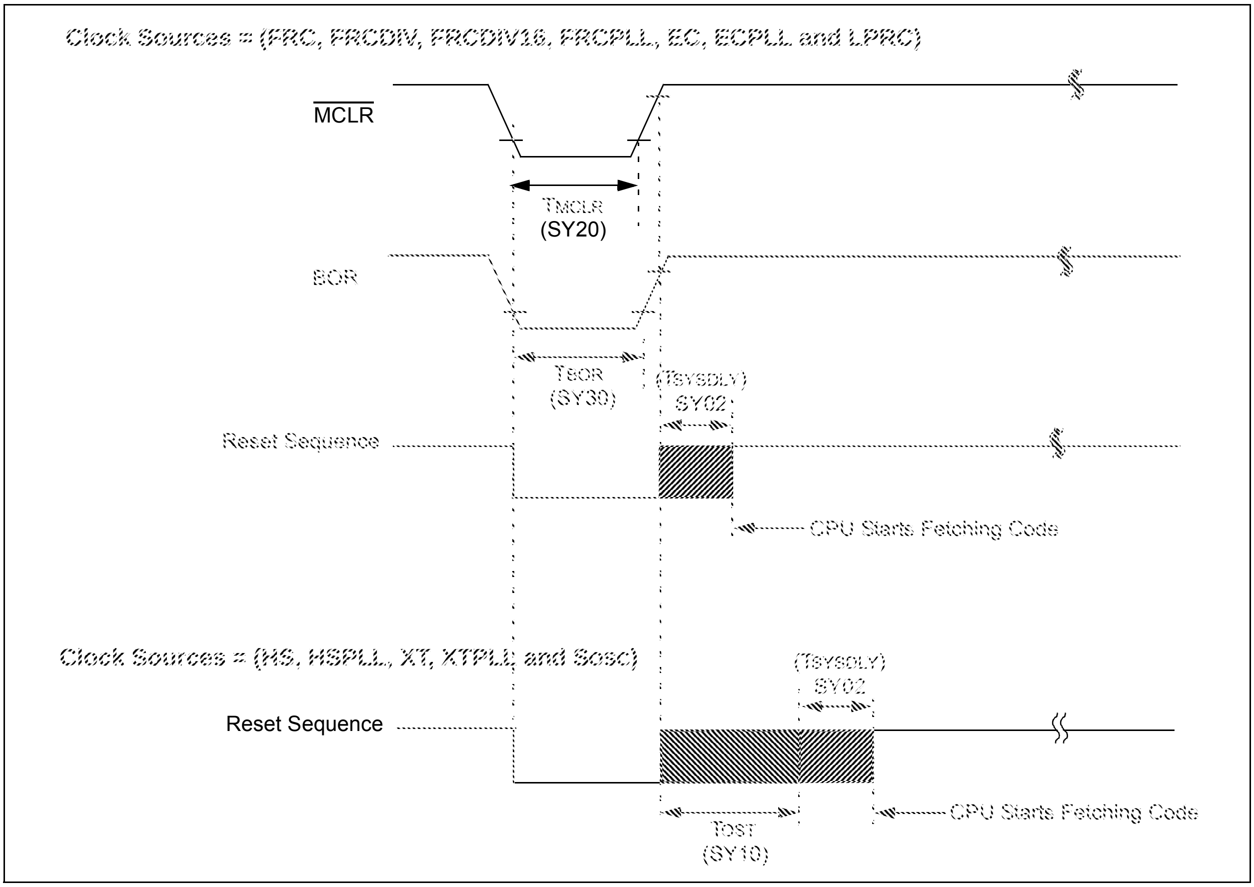


TABLE 30-22: RESETS TIMING

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics[1]**	**Min.**	**Typical[2]**	**Max.**	**Units**	**Conditions**
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	µs	—
SY02	TSYSDLY	System Delay Period: Time Required to Reload Device Configuration Fuses plus SYSCLK Delay before First instruction is Fetched.	—	1 µs + 8 SYSCLK cycles	—	—	—
SY20	TMCLR	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	µs	—
SY30	TBOR	BOR Pulse Width (low)	—	1	—	µs	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typ” column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

TABLE 30-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE) (CONTINUED)

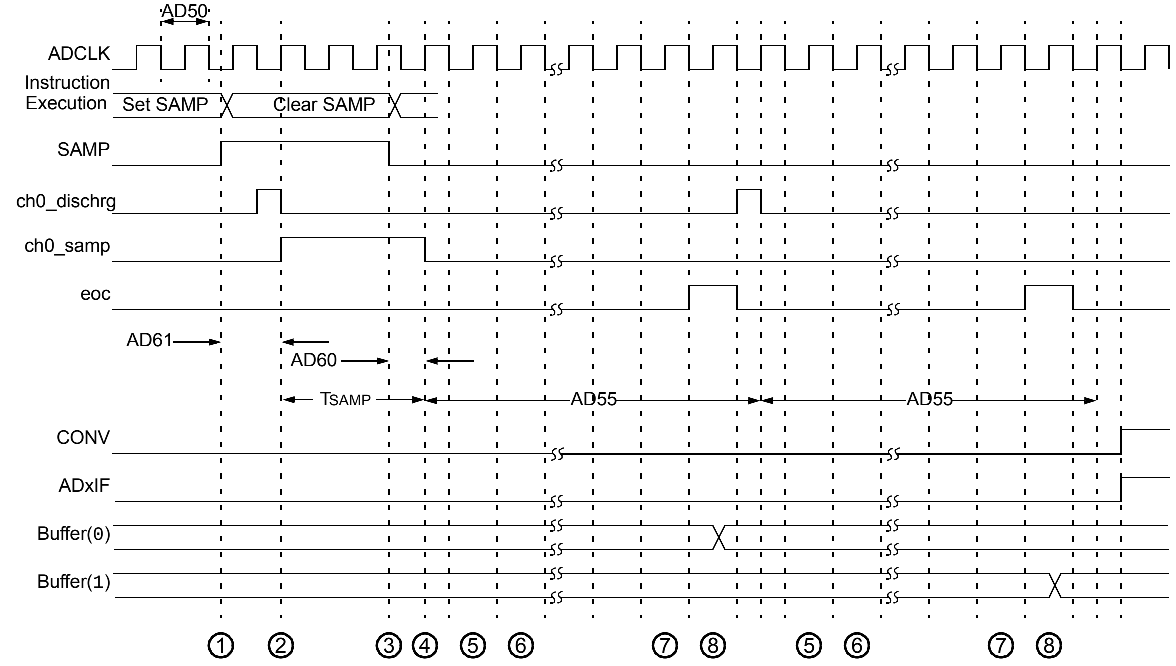
AC CHARACTERISTICS				**Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM40	TAA:SCL	Output Valid from Clock	100 kHz mode	—	3500	ns	—
			400 kHz mode	—	1000	ns	—
			1 MHz mode **(Note 2)**	—	350	ns	—
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	The amount of time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode **(Note 2)**	0.5	—	μs	
IM50	CB	Bus Capacitive Loading		—	400	pF	—
IM51	TPGD	Pulse Gobbler Delay		52	312	ns	See **Note 3**

Note 1: BRG is the value of the I^{2}C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

FIGURE 30-18: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = `0`, SSRC<2:0> = `000`)



① – Software sets ADxCON. SAMP to start sampling.

② – Sampling starts after discharge period. TSAMP is described in **Section 17. “10-bit Analog-to-Digital Converter (ADC)”** (DS60001104) in the *“PIC32 Family Reference Manual”*.

③ – Software clears ADxCON. SAMP to start conversion.

④ – Sampling ends, conversion sequence starts.

⑤ – Convert bit 9.

⑥ – Convert bit 8.

⑦ – Convert bit 0.

⑧ – One TAD for end of conversion.

31.0 50 MHz ELECTRICAL CHARACTERISTICS

This section provides an overview of the PIC32MX1XX/2XX 28/36/44-pin Family electrical characteristics for devices operating at 50 MHz.

The specifications for 50 MHz are identical to those shown in **Section 30.0 “Electrical Characteristics”**, with the exception of the parameters listed in this chapter.

Parameters in this chapter begin with the letter “M”, which denotes 50 MHz operation. For example, parameter DC29a in **Section 30.0 “Electrical Characteristics”**, is the up to 40 MHz operation equivalent for MDC29a.

Absolute maximum ratings for the PIC32MX1XX/2XX 28/36/44-pin Family 50 MHz devices are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias	-40°C to +85°C
Storage temperature	-65°C to +150°C
Voltage on VDD with respect to VSS	-0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to VSS **(Note 3)**	-0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 2.3V **(Note 3)**	-0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to VSS when VDD < 2.3V **(Note 3)**	-0.3V to +3.6V
Voltage on D+ or D- pin with respect to VUSB3V3	-0.3V to (VUSB3V3 + 0.3V)
Voltage on VBUS with respect to VSS	-0.3V to +5.5V
Maximum current out of VSS pin(s)	300 mA
Maximum current into VDD pin(s) **(Note 2)**	300 mA
Maximum output current sunk by any I/O pin	15 mA
Maximum output current sourced by any I/O pin	15 mA
Maximum current sunk by all ports	200 mA
Maximum current sourced by all ports **(Note 2)**	200 mA

Note 1: Stresses above those listed under **“Absolute Maximum Ratings”** may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 30-2).

3: See the **“Pin Diagrams”** section for the 5V tolerant pins.

FIGURE 32-3: TYPICAL I_{PD} CURRENT @ V_{DD} = 3.3V

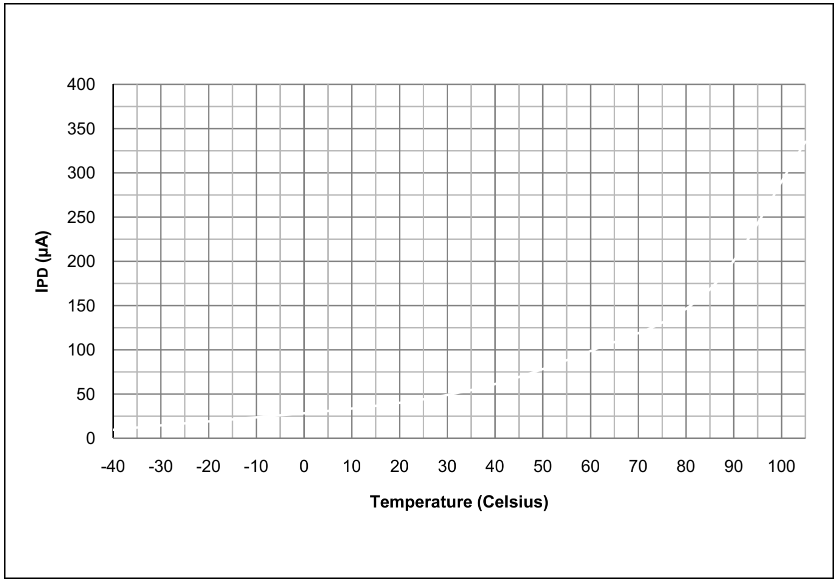


FIGURE 32-4: TYPICAL I_{DD} CURRENT @ V_{DD} = 3.3V

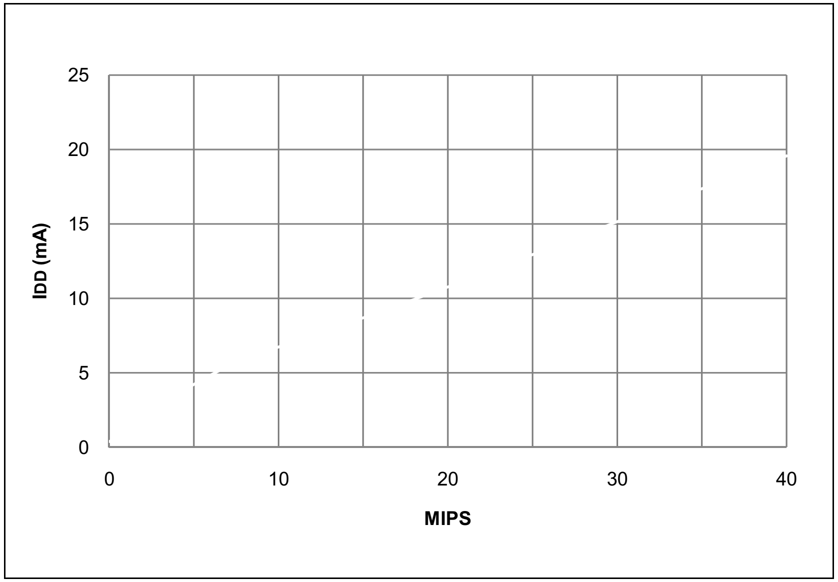
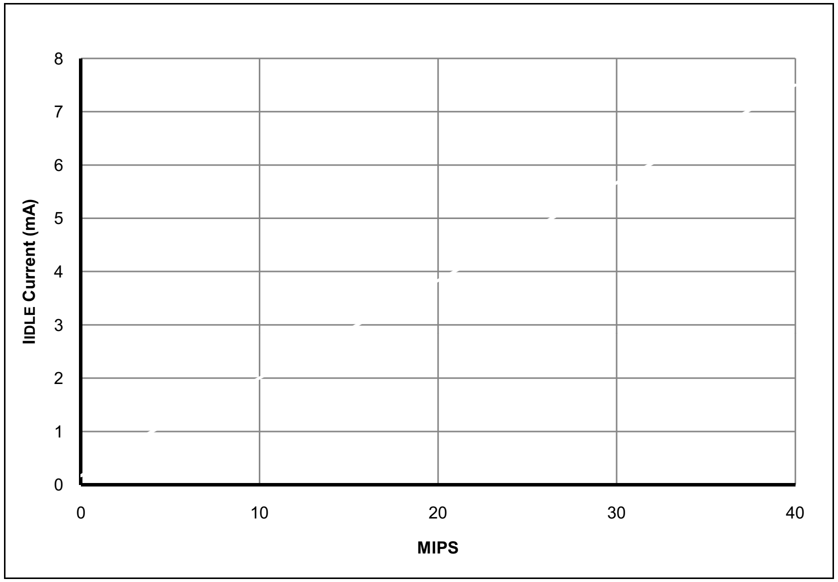


FIGURE 32-5: TYPICAL I_{IDLE} CURRENT @ V_{DD} = 3.3V

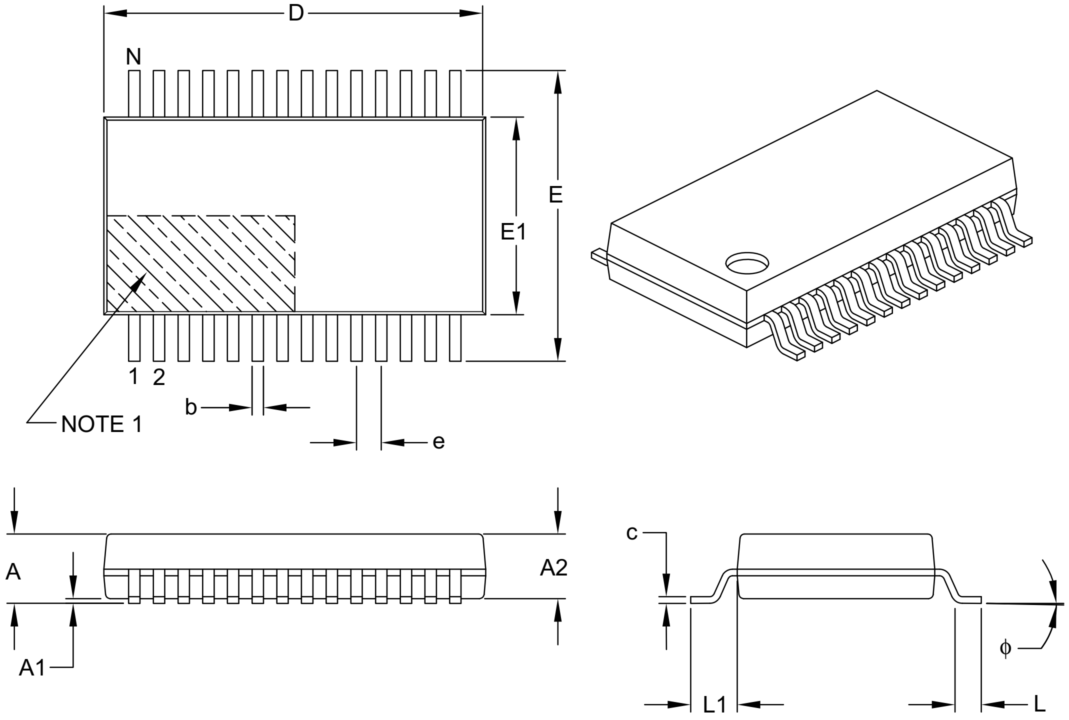


33.2 Package Details

This section provides the technical details of the packages.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	28		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1	1.25 REF		
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

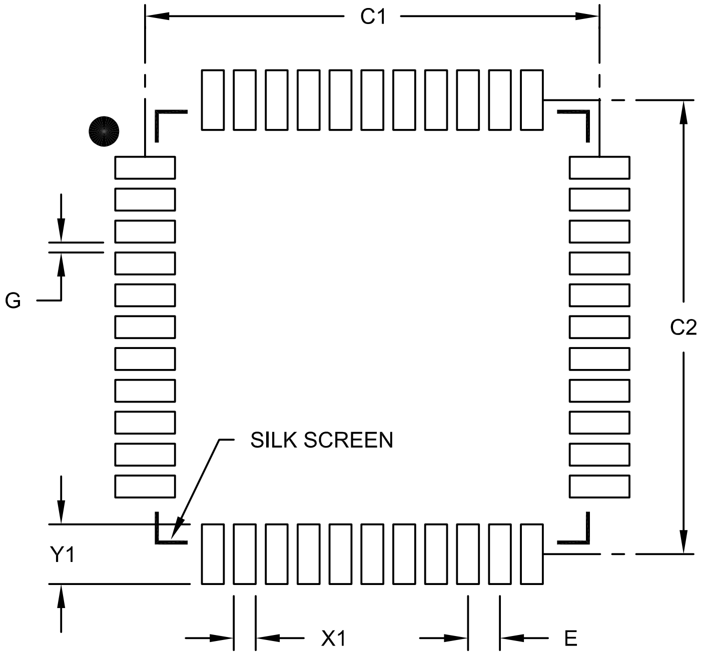
    BSC: Basic Dimension. Theoretically exact value shown without tolerances.

    REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

APPENDIX A: REVISION HISTORY

Revision A (May 2011)

This is the initial released version of this document.

Revision B (October 2011)

The following two global changes are included in this revision:

- All packaging references to VLAP have been changed to VTLA throughout the document
- All references to VCORE have been removed
- All occurrences of the ASCL1, ASCL2, ASDA1, and ASDA2 pins have been removed
- V-temp temperature range (-40ºC to +105ºC) was added to all electrical specification tables

This revision includes the addition of the following devices:

- PIC32MX130F064B
- PIC32MX130F064C
- PIC32MX130F064D
- PIC32MX150F128B
- PIC32MX150F128C
- PIC32MX150F128D
- PIC32MX230F064B
- PIC32MX230F064C
- PIC32MX230F064D
- PIC32MX250F128B
- PIC32MX250F128C
- PIC32MX250F128D

Text and formatting changes were incorporated throughout the document.

All other major changes are referenced by their respective section in Table A-1.

TABLE A-1: MAJOR SECTION UPDATES

Section	Update Description
“32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog**”**	Split the existing Features table into two: PIC32MX1XX General Purpose Family Features (Table 1) and PIC32MX2XX USB Family Features (Table 2). Added the SPDIP package reference (see Table 1, Table 2, and **“Pin Diagrams”**). Added the new devices to the applicable pin diagrams. Changed PGED2 to PGED1 on pin 35 of the 36-pin VTLA diagram for PIC32MX220F032C, PIC32MX220F016C, PIC32MX230F064C, and PIC32MX250F128C devices.
1.0 “Device Overview”	Added the SPDIP package reference and updated the pin number for AN12 for 44-pin QFN devices in the Pinout I/O Descriptions (see Table 1-1). Added the PGEC4/PGED4 pin pair and updated the C1INA-C1IND and C2INA-C2IND pin numbers for 28-pin SSOP/SPDIP/SOIC devices in the Pinout I/O Descriptions (see Table 1-1).
2.0 “Guidelines for Getting Started with 32-bit Microcontrollers”	Updated the Recommended Minimum Connection diagram (see Figure 2-1).